

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT5441016

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SEYONG PARK	03/20/2019
JING LEI	03/13/2019
RENQIU WANG	03/11/2019
JOSEPH BINAMIRA SORIAGA	03/12/2019
JING JIANG	03/16/2019
TINGFANG JI	03/12/2019
JAY KUMAR SUNDARARAJAN	03/07/2019
YELIZ TOKGOZ	03/08/2019
NAGA BHUSHAN	03/12/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	QUALCOMM INCORPORATED
<b>Street Address:</b>	5775 MOREHOUSE DRIVE
<b>City:</b>	SAN DIEGO
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	92121-1714
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	16244978
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(713)623-4846
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	713 623 4844
<b>Email:</b>	gochoa@pattersonsheridan.com, psdocketing@pattersonsheridan.com
<b>Correspondent Name:</b>	PATTERSON & SHERIDAN, L.L.P. QUALCOMM
<b>Address Line 1:</b>	24 GREENWAY PLAZA, SUITE 1600
<b>Address Line 4:</b>	HOUSTON, TEXAS 77046
<b>ATTORNEY DOCKET NUMBER:</b>	181314US
<b>NAME OF SUBMITTER:</b>	PUJA S. DETJEN

<b>SIGNATURE:</b>	/Puja S. Detjen/
<b>DATE SIGNED:</b>	03/26/2019
<b>Total Attachments: 6</b> source=181314_Assignment#page1.tif source=181314_Assignment#page2.tif source=181314_Assignment#page3.tif source=181314_Assignment#page4.tif source=181314_Assignment#page5.tif source=181314_Assignment#page6.tif	

## ASSIGNMENT

WHEREAS, WE,

1. **Seyong PARK**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
2. **Jing LEI**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
3. **Renqiu WANG**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
4. **Joseph Binamira SORIAGA**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
5. **Jing JIANG**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
6. **Tingfang JI**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
7. **Jay Kumar SUNDARARAJAN**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
8. **Yeliz TOKGOZ**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
9. **Naga BHUSHAN**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **TWO-STAGE RESOURCE SPREAD MULTIPLE ACCESS (RSMA) DESIGN** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, or under International Conventions, Treaties, or Agreements, U.S. Application No. 16/244,978, filed **January 10, 2019**, Qualcomm Reference No. 181314, and all provisional applications relating thereto, together with U.S. Provisional Application No. 62/616,992, filed **January 12, 2018**, Qualcomm Reference No. 181314P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known) and divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

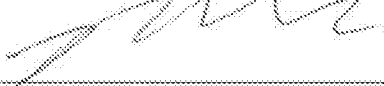
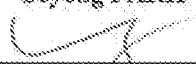
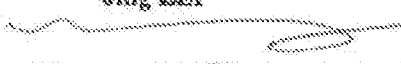
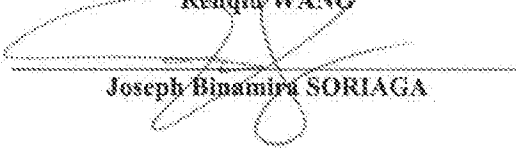
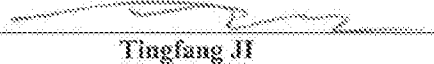
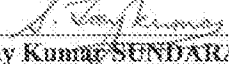
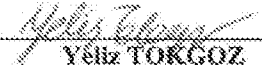

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at <u>San Diego, CA</u> , on <u>3/20/2019</u>	
LOCATION DATE	Seyong PARK
Done at <u>San Diego, CA</u> , on <u>2/13/2019</u>	
LOCATION DATE	Jing LEI
Done at <u>San Diego, CA</u> , on <u>03/11/2019</u>	
LOCATION DATE	Renqiu WANG
Done at <u>San Diego, CA</u> , on <u>3/12/2019</u>	
LOCATION DATE	Joseph Binamira SORIAGA
Done at _____, on _____	_____
LOCATION DATE	Jing JIANG
Done at <u>San Diego, CA</u> , on <u>3/12/2019</u>	
LOCATION DATE	Tingfang JI
Done at <u>San Diego, CA</u> , on <u>March 7, 2019</u>	
LOCATION DATE	Jay Kumar SENDARARAJAN
Done at <u>San Diego, CA</u> , on <u>March 8, 2019</u>	
LOCATION DATE	Yeliz TOKGOZ
Done at <u>SAN DIEGO, CA</u> , on <u>3/12/2019</u>	
LOCATION DATE	Naga BHUSHAN

## ASSIGNMENT

WHEREAS, WE,

1. **Seyong PARK**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
2. **Jing LEI**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
3. **Renqiu WANG**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
4. **Joseph Binamira SORIAGA**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
5. **Jing JIANG**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
6. **Tingfang JI**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
7. **Jay Kumar SUNDARARAJAN**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
8. **Yeliz TOKGOZ**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,
9. **Naga BHUSHAN**, having a mailing address located at **5775 Morehouse Drive; San Diego, California 92121-1714**,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **TWO-STAGE RESOURCE SPREAD MULTIPLE ACCESS (RSMA) DESIGN** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, **QUALCOMM Incorporated** (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at **5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A.**, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, or under International Conventions, Treaties, or Agreements, U.S. Application No. 16/244,978, filed **January 10, 2019**, Qualcomm Reference No. 181314, and all provisional applications relating thereto, together with U.S. Provisional Application No. 62/616,992, filed **January 12, 2018**, Qualcomm Reference No. 181314P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known) and divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;


AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____	, on _____	_____
LOCATION	DATE	Seyong PARK
Done at _____	, on _____	_____
LOCATION	DATE	Jing LEI
Done at _____	, on _____	_____
LOCATION	DATE	Renqiu WANG
Done at _____	, on _____	_____
LOCATION	DATE	Joseph Binamira SORIAGA
Done at <u>San Diego</u>	, on <u>3/16/2019</u>	
LOCATION	DATE	Jing HANG
Done at _____	, on _____	_____
LOCATION	DATE	Tingfang JI
Done at _____	, on _____	_____
LOCATION	DATE	Jay Kumar SUNDARARAJAN
Done at _____	, on _____	_____
LOCATION	DATE	Yeliz TOKGOZ
Done at _____	, on _____	_____
LOCATION	DATE	Naga BHUSHAN